



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Wing-Cheong G. Lai et al. Examiner: Tuan Quach  
Serial No.: 09/782498 Group Art Unit: 2814  
Filed: February 13, 2001 Docket: 303.261US3  
Title: SMALL GRAIN SIZE, CONFORMAL ALUMINUM INTERCONNECTS AND  
METHOD FOR THEIR FORMATION

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/782441	February 13, 2001	303.261US2	SMALL GRAIN SIZE, CONFORMAL ALUMINUM INTERCONNECTS AND METHOD FOR THEIR FORMATION

*All considered*

*TU 3/8/04*

Respectfully submitted,

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 21 day of January, 2004.

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